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| Objective |
| Batch name: Process template |
| This process flows is a guideline on how to spin coat, develop and rinse AZnLOF2020 on substrates as Si, SiO2 and Borofloat, using the Spin Track 1 + 2.  |

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| Step Heading | Equipment | **AZ nLOF 2020 spinning on Si, SiO2, Borofloat** | Comments |
| 1. Pretreatment and spin coat of AZ nLOF 2020
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| * 1. Pretreatment
 | BHF dip*or*Spin Track 1 + 2 | BHF dip for Si substrates (30 sec, H2O 5 min)Inline HMDS for SiO2 and Borofloat |  |
| * 1. Coat wafers
 | Spin Track 1 + 2  | **Resist:** AZ nLOF 2020**Spin:** 30 sec @ 3800 rpm (~2 µm)**Softbake:** 1 min @ 110 °C**Spin Track Flows:**T2 nLOF 2020 2um no HMDS T2 nLOF 2020 2um with HMDS |  |
| 1. UV Exposure
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| * 1. Exposure
 | KS Aligner*or*Aligner-6inch | Hard contact**Exposure dose:** 42 mJ/cm2 (6 sec @ 7 mW/cm2) |  |
| 1. Post Exposure Bake
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| * 1. Post Exposure Bake
 | Spin Track 1 + 2 | **Post Exposure Bake:** 1 min @ 110 °C**Recipe:** T2 nLOF 2020 PEB |  |
| 1. Development, Rinse, and Dry
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| * 1. Develop
 | Developer-TMAH | Develop in AZ 726 MIF, double puddle, 40 seconds each**Recipe:** nLOF 2x40 |  |
| 1. Inspection
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| * 1. Inspection
 | Optical microscope |  |  |